

ABSTRACT

There is disclosed an exposure control method in a lithography system having a resist coating and developing apparatus, a wafer transferring mechanism and an exposure control apparatus. The exposure control method in the lithography system includes the steps of transmitting data of temperature for heat-treating a resist film in the resist coating and developing apparatus to the exposure control apparatus; determining and controlling exposure time based on the temperature data; and exposing the resist film on a wafer which is moved or transferred by the wafer transferring mechanism during the determined exposure time.

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